1) Identify the type of silicon wafer described below:
   a. A primary flat but no secondary flat.
   b. A primary flat and a secondary flat 90° apart.
   c. A primary flat and a secondary flat right next to each other.
   d. A primary flat and a secondary flat 135° apart.

2) If a mask on a (100) Si wafer has a square shaped hole aligned to the \(<110>\) directions, and is wet anisotropically etched to a point, describe the shape of the etched feature.

3) If a mask on a (100) Si wafer has a round shaped hole, and is wet anisotropically etched to a point, describe the shape of the etched feature.

4) If a mask on a (111) Si wafer has a square shaped hole is placed in TMAH, what happens (ignore wafer sides and backside)?

5) What are three anisotropic wet etchants?

6) What is a hillock?

7) What is a plasma?

8) What is a Paschen curve?

9) Describe the sputtering process for etching and for material deposition.

10) Describe plasma etching.

11) Describe RIE and DRIE.